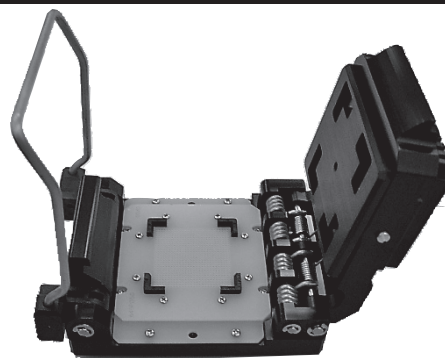
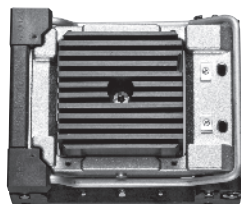


BGA/LGA

BALL/LAND GRID ARRAY

C-series



Specification / 仕様	
Contact resistance (Initial) 接触抵抗 (初期値)	800mΩ or less (At 10 mA)
Maximum voltage 耐電圧	AC700V RMS (for 1 minute)
Insulation resistance 絶縁抵抗	1,000 MΩ or higher (At DC 500V)
Rated current 許容電流値	2A
Operating temperature range 仕様温度	-65°C ~ +150°C
Insertion 機械寿命	Min 5,000 times (Mechanical)

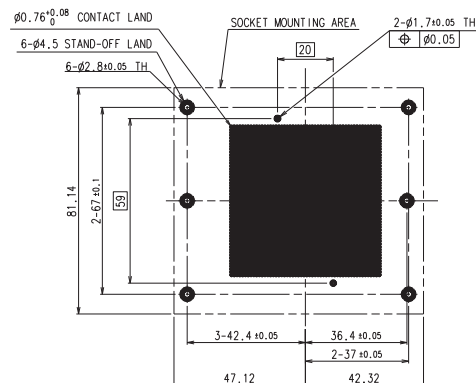
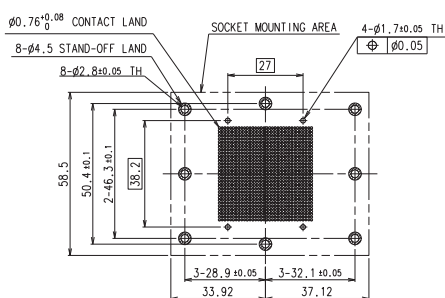
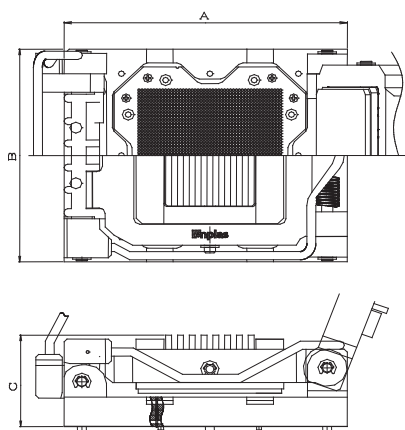
MATERIAL / 材質	
Body 本体	Al, PES
Contact コンタクトピン	Plunger / BeCu, Au plating Spring / SUS, Au plating

※RoHS compliant

KEY CONCEPTS

- Flexible Pitch for 0.8mm and above, flexible pin matrix
- Unique probe pin type contact
- Compression mount
- Replaceable contact module
- RoHS compliant
- Heat-sink with high thermal performance available
- RTD sensor and heater available for thermal control
- Vertically actuated heat-sink design option for bare die
- 0.8mmピッチ以上のマルチピッチ対応
- プローブピンタイプのコンタクトデザイン
- 表面実装
- 交換可能なコンタクトモジュール
- RoHS対応
- 熱解析技術に基づいた最適なヒートシンク設計
- ヒーター・センサーの設置による温度コントロールに対応
- ベアダイタイプのデバイスには垂直作動機構の選択が可能

APPLICABLE IC DIMENSIONS & SOCKET DIMENSIONS



S

L

SOCKET LINE UP

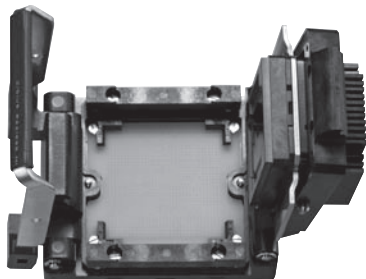
Unit: mm

APPLICABLE IC DIMENSIONS (REF.)				OUT SIDE DIMENSIONS (REF.)			REMARKS
BODY SIZE	PITCH	GRID	MAX PIN COUNT	A	B	C	
~35	S	0.8	34	1156	68.5	57.5	Depending on HS design
		1.0	40	1600			
~55	L	1.0	54	2916	86.9	78.6	
~57.5	XL	1.0	56	3116	106.4	86	

If you need further details or have any questions regarding other models, please contact our local representative.

Applicable IC/BGA · LGA SURFACE MOUNT SOCKET

VC-series

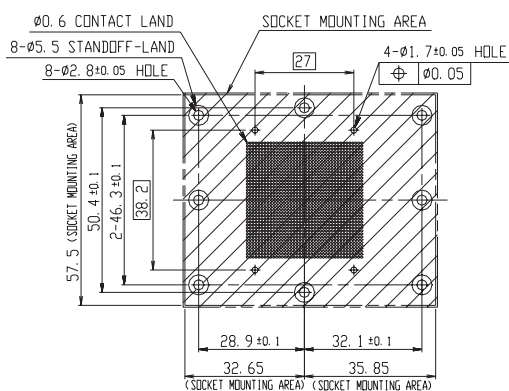


Specification / 仕様	
Contact resistance (Initial) 接触抵抗 (初期値)	100mΩ or less (At 10 mA)
Maximum voltage 耐電圧	AC700V RMS (for 1 minute)
Insulation resistance 絶縁抵抗	1,000 MΩ or higher (At DC 500V)
Rated current 許容電流値	2.5A
Operating temperature range 仕様温度	-65°C ~ +150°C
Insertion 機械寿命	Min 5,000 times
MATERIAL / 材質	
Body 本体	Al, PES
Contact コンタクトピン	BeCu, Au plating

KEY CONCEPTS

- Compression mount
- Replaceable contact module
- RoHS compliant
- Heat-sink with high thermal performance available
- RTD sensor and heater available for thermal control
- Vertically actuated heat-sink design option for bare die
- 表面実装
- 交換可能なコンタクトモジュール
- RoHS対応
- 熱解析技術に基づいた最適なヒートシンク設計
- ヒーター・センサーの設置による温度コントロールに対応
- ベアダイタイプのデバイスには垂直作動機構の選択が可能

APPLICABLE IC DIMENSIONS & SOCKET DIMENSIONS



S

SOCKET LINE UP

Unit: mm

APPLICABLE IC DIMENSIONS (REF.)				OUT SIDE DIMENSIONS (REF.)			REMARKS
BODY SIZE		PITCH	GRID	MAX PIN COUNT	A	B	
~35	S	0.8	41	1681	68.5	57.5	Depending on HS design
		1.0	34	1156			
~52.5	L	1.0	51	2601	86.9	78.6	

If you need further details or have any questions regarding other models, please contact our local representative.